

Lecture 3:

MEMS fabrication I: bulk micromachining (2)

- p3

$$AR = h / w$$

If sensitivity is 1:3, and mask is 20um, then we could fabricate 60um deep.

Usually RIE allows 50um depth.

- p27

At 300~400 degree, only the interface melt and adhere.

Roughness of Si is important. (Angstrom level)